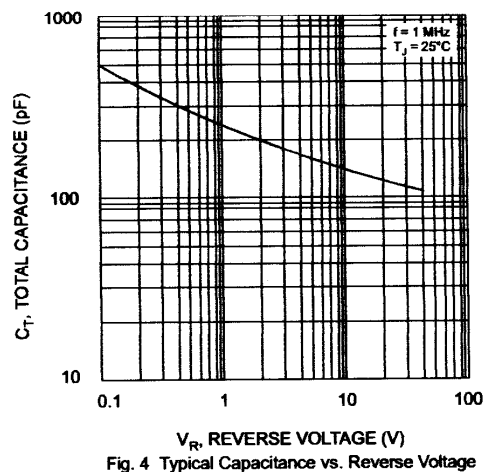
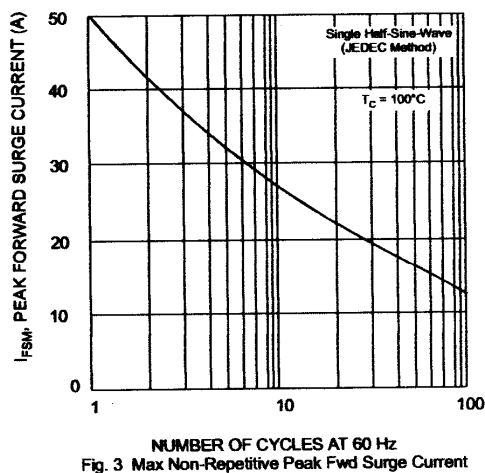
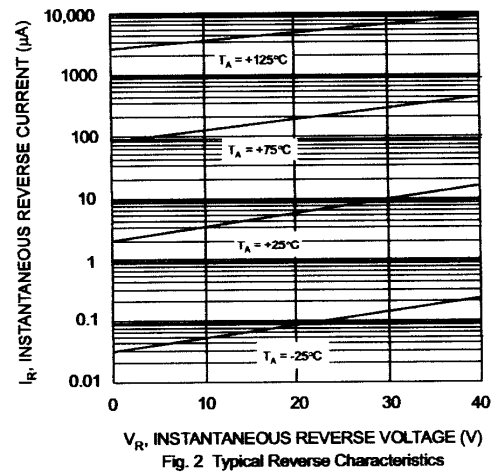
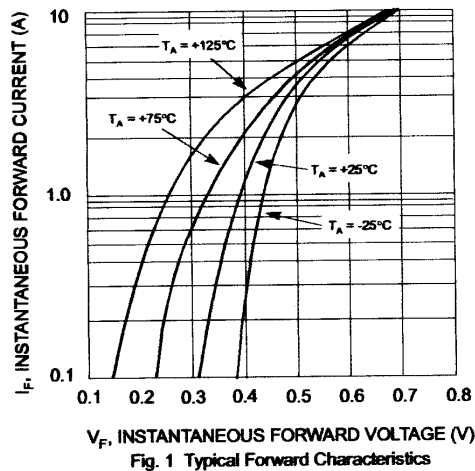
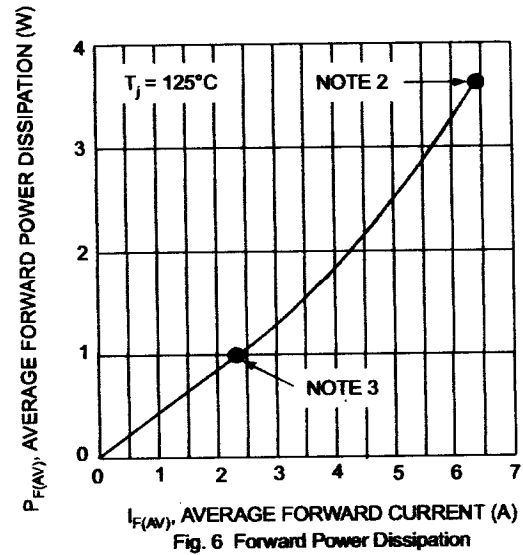
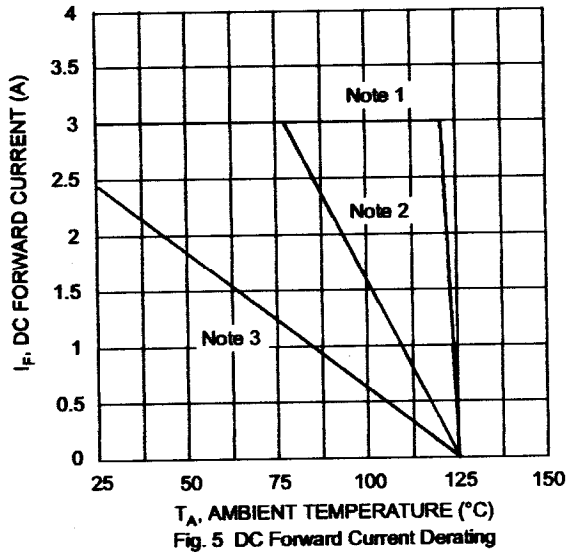


ELECTRICAL PARAMETERS @ 25°C (unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ.	Max	Units
Forward Voltage (Note 1)	V_F	$I_F = 3\text{ A}, T_J = 25^\circ\text{C}$ $I_F = 3\text{ A}, T_J = 125^\circ\text{C}$ $I_F = 6\text{ A}, T_J = 25^\circ\text{C}$ $I_F = 6\text{ A}, T_J = 125^\circ\text{C}$		0.46 0.40 0.57 0.54	0.50 0.44 0.61 0.58	V
Reverse Break Down Voltage (Note 1)	V_{BR}	$I_R = 0.5\text{ mA}$	40			V
Reverse Current (Note1)	I_R	$V_R = 40\text{V}, T_J = 25^\circ\text{C}$ $V_R = 40\text{V}, T_J = 100^\circ\text{C}$		15 10	500 20	μA mA
Capacitance	C_T	$V_R = 4\text{ V}; f = 1\text{ MHz}$		180		pF

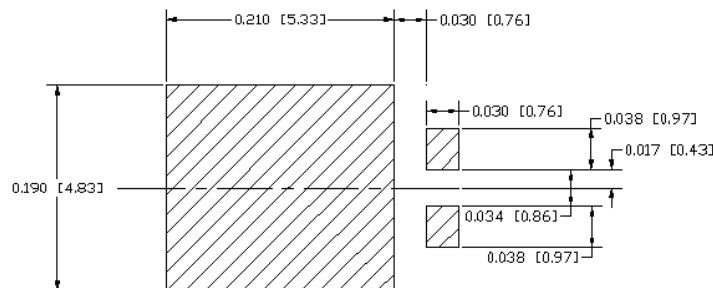
Note: 1 Short duration test pulse used to minimize self – heating effect.

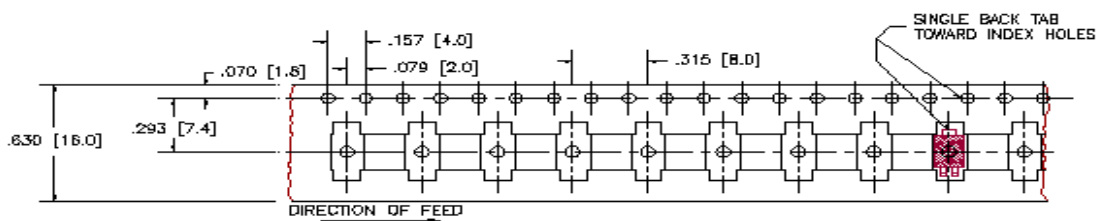
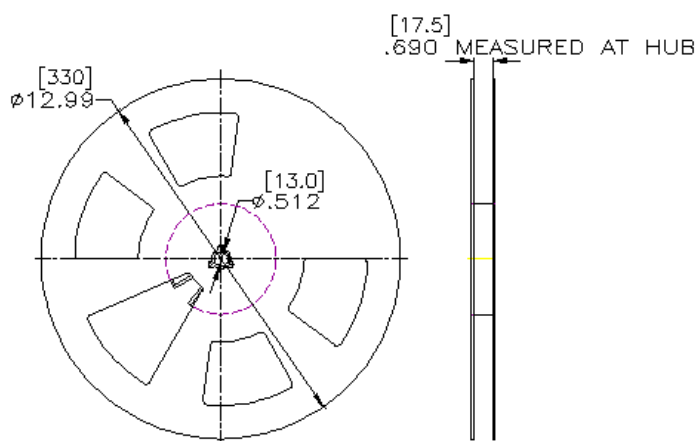


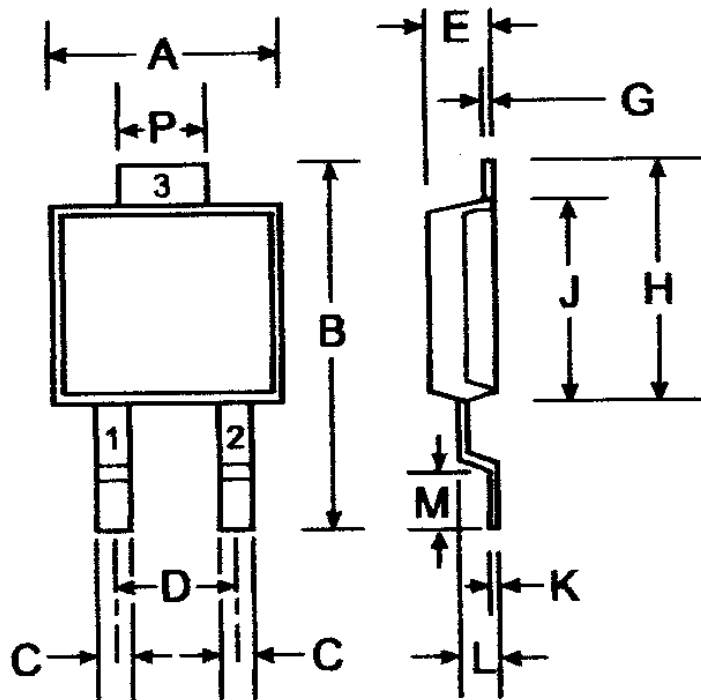


- Notes:
1. $T_A = T_{\text{SOLDERING POINT}}$, $R_{\theta JS} = 3.2^\circ \text{C/W}$, $R_{\theta SA} = 0^\circ \text{C/W}$.
 2. Device mounted on GETEK substrate, 2" x 2", 2 oz. copper, double-sided, cathode pad dimensions 0.75" x 1.0", anode pad dimensions 0.25" x 1.0". $R_{\theta JA}$ in range of 20-40° C/W.
 3. Device mounted on FRA-4 substrate, 2" x 2", 2 oz. copper, single-sided, pad layout $R_{\theta JA}$ in range of 65° C/W. See mounting pad below.

MOUNTING PAD DIMENSIONS (inches)



TAPE & REEL

13 INCH REEL


PACKAGE DIMENSIONS


PIN 1 ○
 PIN 2 ○
 PIN 3, BOTTOMSIDE
 HEAT SINK

Note: Pins 1 & 2 must be electrically connected at the printed circuit board.

POWERMITE®3		
Dim	Min	Max
A	4.03	4.09
B	6.40	6.61
C	.889 NOM	
D	1.83 NOM	
E	1.10	1.14
G	.178 NOM	
H	5.01	5.17
J	4.37	4.43
K	.178 NOM	
L	.71	.77
M	.36	.46
P	1.73	1.83
All Dimensions in mm		



UPS340e3

3 A LOW Vf Schottky Barrier Rectifier

NOTES:

www.Microsemi.COM

UPS340e3
NOTES